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supervisor was Kimberly A. Goff, and the production supervisor was
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Dry Print Screened resistors and conductors that have been processed through the drying cycle, removing the solvents from the thick-film paste, but not yet fired.

Dry Strength The strength of an adhesive joint determined immediately after drying under specified conditions or after a period of conditioning in the standard laboratory atmosphere. *See also Wet Strength.*

Dual in-Line Package (DIP) An electronic package containing an integrated circuit chip which is connected to terminals or leads that are positioned in two straight rows on the sides of the package, and have standard spacings between the leads and between the rows of leads. These leads are oriented perpendicular to the seating plane for inserting into interconnecting holes in a substrate. *See Fig. 3.*

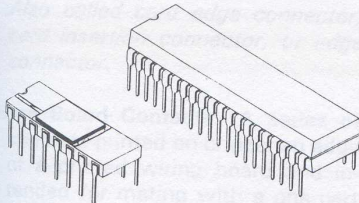


Figure 3: Dual in-Line

Dual-Wave Soldering A soldering process that utilizes both a turbulent wave and a laminar wave. The turbulent wave gets into small, constricted areas to ensure good coverage, while the laminar wave

removes solder projections. *See also Wave Soldering.*

Ductility The ability of a material to deform plastically before fracturing.

Dummy Connector Plug A part included in the total design of a connector to mate with a connector but not to perform an electrical function.

Dummy Connector Receptacle A part included in the total design of a connector that mates with a plug connector but cannot be attached to a cable. It is used to seal out moisture.

Dumming A process in which a metal plate having a large total area is placed in an electroplating solution, attached to the cathode, and used for removing impurities from the solution.

Durometer An instrument used to measure the hardness of a nonmetal such as rubber or plastic. Available in different types to cover the ranges of soft, medium, and hard materials.

Duty Cycle The specified operating and nonoperating times of equipment.

Dye Penetrant A liquid material containing fluorescent particles, usually red, and a carrier fluid that is used to detect cracks in solid parts or to locate a gross leak in a sealed electronic package.